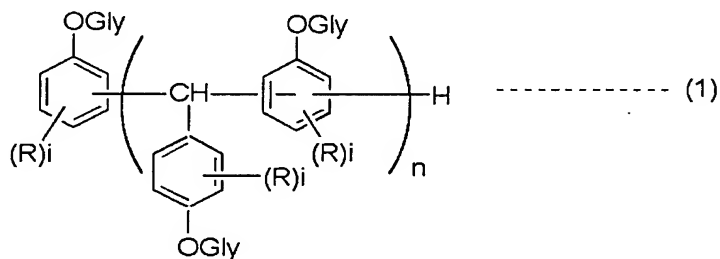


What is claimed is:

1. A resin film comprising (A) an epoxy resin having two or more glycidyl groups in a molecule, (B) an epoxy resin curing agent, (C) a thermoplastic resin, and (D) a filler, wherein the filler content in at least either one of the surface regions on the cross-section of the film is less than the filler concentration in the central region.
2. A resin film according to claim 1, wherein two or more films are laminated.
3. A resin film according to claim 1 or 2, wherein epoxy resin (A) having two or more glycidyl groups in a molecule is represented by following formula (1)



wherein, n represents an average repeating number of 1 to 10; a plurality of R each independently represents hydrogen atom, an alkyl group having 1-10 carbon atoms, an aralkyl group having 6-20 carbon atoms, an aromatic group having 6-20 carbon atoms, a cycloalkyl group having 5-7 carbon atoms or a hydrocarbon group having 6-20 carbon atoms containing a cycloalkyl group having 5-7 carbon atoms; i each independently represents an integer of 1-4; and Gly represents glycidyl group.

4. A resin film according to any one of claims 1 to 3, wherein epoxy resin curing agent (B) is phenol novolak.
5. A resin film according to any one of claims 1 to 3, wherein thermoplastic resin (C) is polyether sulfone.
6. A resin film according to any one of claims 1 to 3, wherein filler (D) is silica.
7. A multilayer printed wiring board comprising an insulating layer obtained by curing the resin film according to any one of claims 1 to 6.